



Miller 2-1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Patent Application**

Applicant(s): C.J. Miller et al.  
Case: 2-1  
Serial No.: 10/786,182  
Filing Date: February 25, 2004  
Group: To Be Assigned  
Examiner: To Be Assigned

I hereby certify that this paper is being deposited on this date with the U.S. Postal Service as first class mail addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Signature: *[Handwritten Signature]*

Date: April 9, 2004

Title: Methods and Apparatus for Integrated Circuit Ball Bonding  
with Substantially Perpendicular Wire Bond Profiles

TRANSMITTAL OF FORMAL DRAWINGS

Mail Stop PGPUB Drawings  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Attention: Official Draftsperson

Sir:

Applicants submit herewith four (4) sheets of formal drawings in the above-referenced application.

Respectfully submitted,

*[Handwritten Signature: Joseph B. Ryan]*

Date: April 9, 2004

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